

Max TC Power Plus (G4)®

Extreme - Thermal Forcing System. Exceptionally Powerful, Low Temp & Reliable.





Selected heads: Reduced (45 mm), Standard (55mm), Enlarged (75 mm)

MD Thermal control units were designed with high efficiency and flexibility in mind, allowing for customization to suit different package and interface variations. The system allows for temperature forcing across a wide range of device sizes and types, whether socketed or soldered to the board. With state of the art design and technology MD units stimulate the DUT to the desired temperature precisely and consistently via direct contact with a thermal head's tip.

The well proven thermal head methodology creates a stable temperature control environment right where you need. The pneumatically driven thermal head makes direct contact with the IC device providing great power handling and precise temperature control.

The G4 series features upgrades that include extended temperature range, low current consumption, low noise level, lower air temp emission with increased cooling power.

3 models are available at your choice:



45 mm footprint & elongated nose allows for an improved keep out area to test <45mm socketed and soldered devices mm where the connectors and cables are very close to the DUT.

Standard head

55 mm footprint is more suitable for testing socketed and soldered standard devices up to 55 mm.



75 mm footprint is more suitable for testing large socketed and soldered devices or modules up to 100 mm.

Features:

- Temperature range -75°C to 200°C
- Cooling power -50°C @ 400W (Tc)
- Temperature stability 0.2°C
- Self-contained liquid free operation
- . Quiet and portable
- Adapt to most packages and sockets
- Condensation FREE
- Maintenance FREE
- Remotely controlled via an ethernet
- Fully programmable for automation
- Tj and Tc control
- Environmentally friendly operation

Available Options:

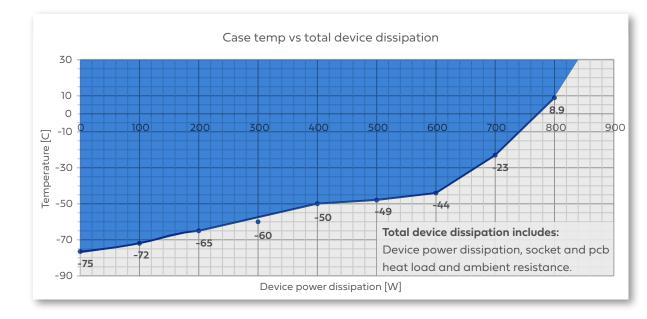
MDMTC-2PP-ADD2

- Clip-on actuator
- Manual actuator
- Toggle clamp
- Boom stand
- Customized fixtures
- Enclosures

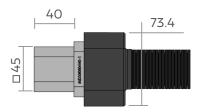
Applications:

- ATE, SLT and bench
- High reliability testing
- OEM integrations
- LN2/thermal stream/chiller replacement

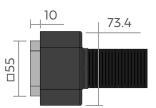




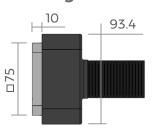
Reduced head



Standard head



Enlarged head



SYSTEM SPECIFICATIONS:

Operating

Facilities

Get Full Data Sheet

Mechanical Data

Data Communication

